

IN THE CLAIMS

This listing of claims replaces all prior listing and versions of the claims in the present application.

Listing of Claims:

Claims 1-42 (Canceled).

Claim 43 (Currently Amended): Microstructure comprising ~~in a first layer insulated from a substrate by an insulator layer at least one sensitive element connected to at least one contact pad by an electrical connection and protected by a package cap, wherein the at least one sensitive element, the electrical connection and the contact pad form an assembly delimited in a first layer by at least one trench, said assembly being covered by the package cap, at least one contact pad and at least one sensitive element connected to said at least one contact pad by an electrical connection, said sensitive element, said contact pad and said electrical connection forming an assembly, said assembly comprising a first layer insulated from a substrate by an insulator layer, said assembly including at least one trench in the first layer, said assembly being covered by a package cap, said package cap comprising at least one opening above the at least one contact pad and being integral with, on the one hand, the contact pad on the edges of the opening and, on the other hand, a zone of the first layer located beyond the trench in relation to the assembly.~~

Claim 44 (Previously Presented): Microstructure according to claim 43, wherein the package cap is sealed in a leak tight manner in such a way as to define a leak tight cavity in which is located the at least one sensitive element.

Claim 45 (Previously Presented): Microstructure according to claim 44, wherein the package cap comprises at least one orifice capable of being sealed by a plug in such a way as to be able to control an atmosphere of said cavity.

Claim 46 (Previously Presented): Microstructure according to claim 43, wherein the electrical connection, the contact pad and the sensitive element are formed of a same material.

Claim 47 (Previously Presented): Microstructure according to claim 43, wherein the package cap is formed of a dielectric material.

Claim 48 (Previously Presented): Microstructure according to claim 43, wherein the package cap is formed of a semi-conductor or conductor material.

Claim 49 (Previously Presented): Microstructure according to claim 48, wherein the assembly and the package cap are formed of a same conductor or semi-conductor material.

Claim 50 (Previously Presented): Microstructure according to claim 48, wherein a dielectric layer insulates the package cap from the contact pad..

Claim 51 (Previously Presented): Microstructure according to claim 48, wherein a dielectric layer insulates the package cap from the zone of said first layer located beyond the at least one trench in relation to the assembly.

Claim 52 (Previously Presented): Microstructure according to claim 43, wherein the contact pad is covered with a conductive band located inside the at least one opening.

Claim 53 (Previously Presented): Microstructure according to claim 43, wherein the package cap comprises at least one pillar resting on a zone of the at least one sensitive element.

Claim 54 (Previously Presented): Microstructure according to claim 53, wherein the zone of the at least one sensitive element is fixed to the substrate.

Claim 55 (Previously Presented): Microstructure according to claim 53, wherein the package cap is formed in a conductor or semi-conductor material, and comprises at least one pillar that rests on a zone of the at least one sensitive element, the package cap and the pillar contributing to forming an electrical connection with said zone of said at least one sensitive element.

Claim 56 (Previously Presented): Microstructure according to claim 53, wherein the package cap is formed of a conductor or semi-conductor material and the at least one pillar is electrically insulated from the at least one sensitive element.